



LEADING MOBILE CONVERGENCE

PRESS RELEASE

For immediate release

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HelloSoft to showcase its highly optimized VoIP at TI's Mobile Services Forum

San Jose, CA, September 4, 2007 — HelloSoft, Inc. a leading provider of VoIP and IMS/VCC technologies for mobile devices will showcase its flagship VoIP products at Texas Instruments Mobile Services Forum to be held at the Imperial, Janpath in New Delhi on September 6, 2007.

HelloSoft will demonstrate its flagship power-efficient and low-footprint comprehensive SIP-based VoIP product (HelloMobileCommunicator-Lite™) on TI's OMAP850 and OMAPV1030 processors with windows mobile 5.0 OS. HelloMobileCommunicator-Lite runs on a single-RISC Core. This product is the industry's most optimized and power-efficient VoIP solution for mobile handsets. It is trusted by tier-one handset OEMs/ODMs and Semiconductor vendors and has been widely interop-tested with major commercial SIP servers.

HelloSoft, Inc. is a veteran member of TI's OMAP™ Developer Network, a group of leading software developers porting advanced applications to TI's high performance, power-efficient OMAP processors. Handset manufacturers adopting OMAP devices enjoy the rapid deployment of compelling wireless applications – including streaming audio and video, multimedia messaging, gaming, security, speech recognition, location based services and mobile commerce – across all leading operating systems. Systems level integration services are also provided worldwide by independent OMAP Technology Centers. The OMAP platform has been selected by leading manufacturers, such as Nokia, Palm, NEC, Fujitsu, LG Electronics, Hewlett-Packard, Sendo, HTC and many more, for their 2.5 and 3G wireless devices. For more information, please visit www.ti.com/omap.

About HelloSoft

HelloSoft is the world's leading provider of VoIP Technologies for wireline and wireless devices. The company enables mass deployment of low-cost, power-efficient, fully-featured multi-mode wireline and wireless devices by providing highly optimized RISC-based VoIP software products with superior voice quality, QoS, and efficient call switching specifically designed for next generation end-points. HelloSoft's IMS/VCC technology enables seamless hand-off between cellular and Wi-Fi networks for multi-mode handsets. This comprehensive portfolio of award winning VoIP products enables OEMs, ODMs and semiconductor manufacturers to deliver VoIP enabled products with a short time to market schedule.

HelloSoft is headquartered in San Jose, California with an R&D facility in Hyderabad. HelloSoft's customers include leading technology firms such as Skype, HTC, BenQ, CEC, Thrane & Thrane, Toshiba, Panasonic, Accton, Wistron NeWeb, NeoMagic, a la Mobile and 5V Technologies along with top semiconductor manufacturers, Original Device Manufacturers (ODMs) and Original Equipment Manufacturers (OEMs) globally. HelloSoft's partners include Texas Instruments, Intel, LongBoard, Arm, MIPS, Microsoft and Symbian. Please visit our website www.hellosoft.com for further information.

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